

GXO-5332 - 2.5~3.3V Tight Stability Oscillator

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Adhesive	Silicon resin	Si	7440-21-3	0.004	10.53
	Silver powder	Ag	7440-22-4	0.034	89.47
Ceramic base	Alumina	Al ₂ O ₃	1344-28-1	35.450	71.82
	Alumina	SiO ₂	14808-60-7	1.130	2.29
	Alumina	Cr ₂ O ₃ (Non hex)	1308-38-9	0.180	0.36
	Alumina	Mo	7439-98-7	0.240	0.49
	Gold plating	Au	7440-57-5	1.160	2.35
	Kovar ring	Fe	7439-89-6	3.480	7.05
	Kovar ring	Ni	7440-02-0	1.870	3.79
	Kovar ring	Co	7440-48-4	1.102	2.23
	Nickel plating	Ni	7440-02-0	1.940	3.93
	Tungsten/Molybdenum	W	7440-33-7	2.720	5.51
Tungsten/Molybdenum	Mo	7439-98-7	0.090	0.18	
Chip (IC)	Electrode pad	Cu	7440-50-8	0.000	0.00
	Gold wire	Au	7440-57-5	1.020	73.12
	Silicon material	Si	7440-21-3	0.374	26.81
	Wiring material	Al	7429-90-5	0.001	0.07
Crystal blank	Synthetic quartz	SiO ₂	14808-60-7	2.020	100.00
Electrode	Chromium	Cr	7440-47-3	0.000	0.00
	Gold	Au	7440-57-5	0.040	100.00
Metal Cap	Electroless Nickel plating	Ni	7440-02-0	0.330	5.11
	Electroless Nickel plating	P	7723-14-0	0.040	0.62
	Kovar	Fe	7439-89-6	3.270	50.62
	Kovar	Ni	7440-02-0	1.780	27.55
	Kovar	Co	7440-48-4	1.040	16.10

Total Mass: 59.315 mg



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